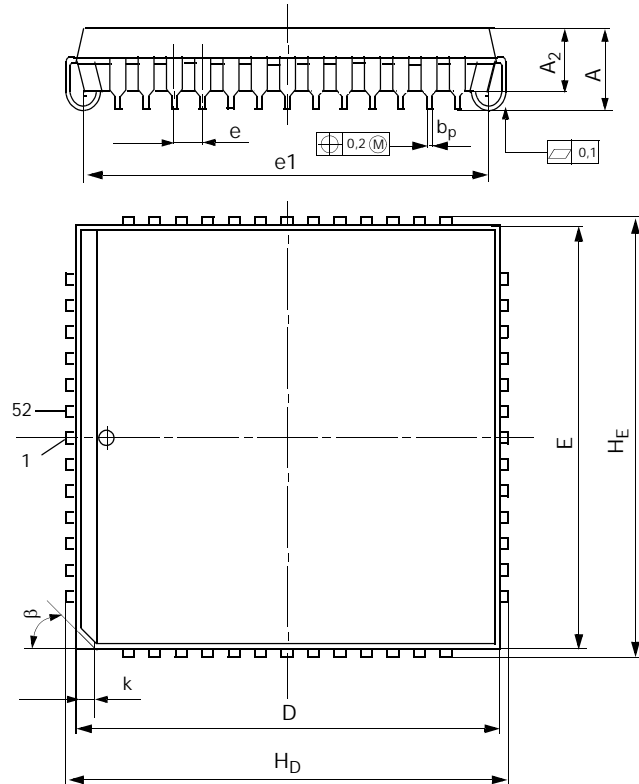


Based on IEC 191-2Q: Type 112E11

Dimensions in millimetres

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	5,10
b_{Pmin}	0,33
b_{Pmax}	0,53
e	1,27
H_{Dmin}	19,90
H_{Dmax}	20,20
H_{Emin}	19,90
H_{Emax}	20,20

- 2 **Weight** $\leq 3,2$ g
- 3 **Package Body Material** Low Stress Epoxy
- 4 **Lead Material** FeNi-Alloy or Cu-Alloy
- 5 **Lead Finish** solder plating
- 6 **Lead Form** J-bends

Dimensions of Sub-Group C1	
A_{min}	4,19
A_{2min}	3,10
A_{2max}	3,96
D_{min}^*	19,05
D_{max}^*	19,20
E_{min}^*	19,05
E_{max}^*	19,20
k_{min}	1,00
β	45°
e_{1min}	17,50
e_{1max}	18,55

* without mold-flash

Zentrum Mikroelektronik Dresden GmbH		
Editor: signed Schoder	Date: 13.11.95	Doc-No. QS-000732-HD-02
Check: signed Wilde	Quality: signed Lorenz	